Syncor (MCOTS-C-28-50-HZ Single Output Half-brick
MILITARY COTS DC-DC	CONVERTER
	DA 95% @ 5A / 94% @ 10A tput Efficiency
Full Power Operation: -55°C to	o +100°C
The MilQor [®] series of Mil-COTS DC-DC converters brings SynQor's field proven high-efficiency synchronous	MilCOTS [®]
ectification technology to the Military/Aerospace ndustry. SynQor's ruggedized encased packaging	
pproach ensures survivability in demanding environments. Compatible with the industry standard	
ormat, these converters operate at a fixed frequency,	MCOTS-C-28-50-HZ-N-M DC-DC CONVERTER 28 _{IN} 50V _{OUT} @ 10A
nd follow conservative component derating guidelines. They are designed and manufactured to comply with a	SIN SERIAL NUM DIC DC - NOT CAGE CODE (WXID SIN SERIAL NUM DIC DC - NOT CAGE CODE (WXID III TIM SHARE- SHARE- ONOFE +III
vide range of military standards.	9444
hae range of finitary standards	

Mechanical Features

- Industry standard half-brick pin-out
- Size: 2.49" x 2.39" x 0.51"
- (63.1 x 60.6 x 13.0 mm)
- Total weight: 5.2 oz. (146 g)
- Flanged baseplate version available

Operational Features

- High efficiency, 94% at full rated load current
- Operating input voltage range: 16-40V
- Fixed frequency switching provides predictable EMI
- No minimum load requirement

Specification Compliance

MCOTS series converters (with an MCOTS filter) are designed to meet: • MIL-HDBK-704 (A-F)

- RTCA/DO-160E Section 16
- MIL-STD-1275 (B,D)
- DEF-STAN 61-5 (Part 6)/(5 or 6)
- MIL-STD-461 (C, D, E, F)

- On/Off control referenced to input return
- Remote sense for the output voltage
- Wide output voltage trim range of +10%, -50%
- Optional: Active current share for parallel applications

Protection Features

- Input under-voltage lockout
- Output current limit and short circuit protection
- Active back bias limit
- Auto-recovery output over-voltage protection
- Thermal shutdown

Screening/Qualification

- AS9100 and ISO 9001 certified facility
- Qualified to MIL-STD-810
- Available with S-Grade or M-Grade screening
- Pre-cap inspection per IPC-A-610, Class III
- Temperature cycling per MIL-STD-883, Method 1010, Condition B, 10 cycles
- Burn-In at 100 °C baseplate temperature
- Final visual inspection per MIL-STD-883, Method 2009
- Full component traceability

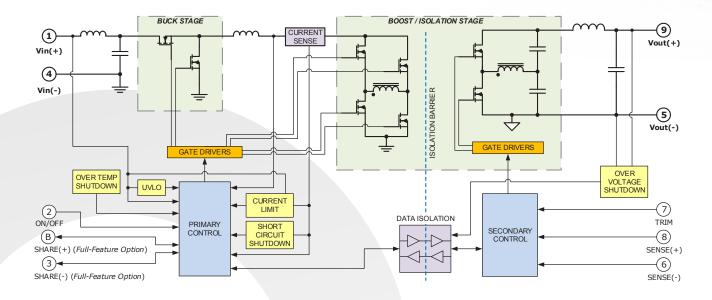
005-0005308 Rev. I



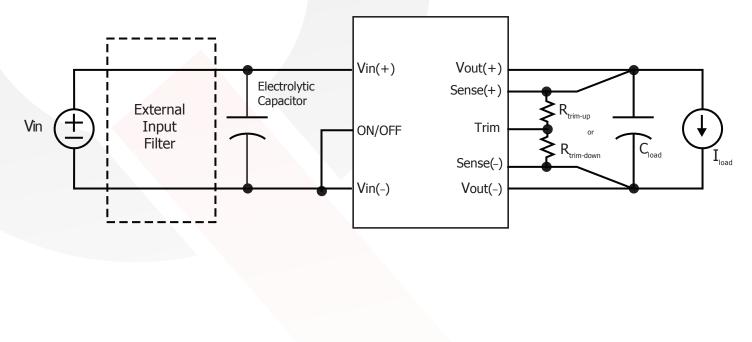
MCOTS-C-28-50-HZ Output: 50V Current: 10A

IX.

BLOCK DIAGRAM



TYPICAL CONNECTION DIAGRAM





MCOTS-C-28-50-HZ ELECTRICAL CHARACTERISTICS

Ta = 25 °C, Vin = 28dc unless otherwise noted; full operating temperature range is -55 °C to +100 °C baseplate temperature with appropriate power derating. Specifications subject to change without notice.

Parameter	Min.	Тур.	Max.	Units	Notes & Conditions
ABSOLUTE MAXIMUM RATINGS					
Input Voltage					
Non-Operating	-1		60	V	Continuous
Operating			40	V	Continuous
Operating Transient Protection			50	V	100 ms transient, square wave
Isolation Voltage					
Input to Output			2250	Vdc	Basic Insulation, Pollution Degree 2
Input to Base-Plate			2250	Vdc	
Output to Base-Plate			2250	Vdc	
Operating Temperature	-55		100	°C	Baseplate temperature
Storage Temperature	-65		135	°C	
Voltage at ON/OFF input pin	-2		18	V	
INPUT CHARACTERISTICS					
Operating Input Voltage Range	16	28	40	V	50V transient for 100 ms
Input Under-Voltage Lockout					
Turn-On Voltage Threshold	15.1	15.4	15.9	V	
Turn-Off Voltage Threshold	14	14.5	15	V	
Lockout Voltage Hysteresis	0.5	0.9	1.5	V	
Recommended External Input Capacitance		470		μF	Typical ESR 0.1-0.2 Ω
Input Filter Component Values $(C_1 \setminus L \setminus C_2)$		47\0.34\23		nF\µH\µF	Internal values; see Figure E
Maximum Input Current			41	A	At Low Line, Full Load and Trimmed up 10%
No-Load Input Current		340	430	mA	
Disabled Input Current		100	125	mA	
Response to Input Transient		1.5		V	0.25 V/µs input transient; See Figure 12
Input Terminal Ripple Current		500		mA	RMS
Recommended Input Fuse			40	A	Fast blow external fuse recommended
OUTPUT CHARACTERISTICS		_			
Output Voltage Set Point	49.18	50.00	50.70	V	
Output Voltage Regulation					See Note 1
Over Line		±0.25\125		%\mV	
Over Load		±0.25\125		%\mV	
Over Temperature		±0.380	±1.250	V	
Total Output Voltage Range	48.50		51.50	V	Over sample, line, load, temperature & life
Output Voltage Ripple and Noise					20 MHz bandwidth; See Note 2
Peak-to-Peak		250	300	mV	Full Load
RMS		60	75	mV	Full Load
Operating Output Current Range	0		10	A	Subject to thermal derating
Output DC Current-Limit Inception	11	12	13	A	Output Voltage 10% Low
Output DC Current-Limit Shutdown Voltage		20		V	See Note 3
Back-Drive Current Limit while Enabled	2	3	4	A	Negative current drawn from output
Back-Drive Current Limit while Disabled	0	3	8	mA	Negative current drawn from output
Maximum Output Capacitance			1	mF	10 A Resistive Load
Output Voltage during Load Current Transient					
Step Change in Output Current (0.1 A-5 A/µs)		2		V	50% to 75% to 50% IOUT max, 100 µF load cap
Settling Time		8		ms	To within 1% VOUT nom
Output Voltage Trim Range	-50		10	%	Across Pins 8 & 6; Figure C
Output Over-Voltage Protection	56.5	59	61.5	V	Over full temp range
EFFICIENCY					
100% Load		94		%	See Figure 1 for efficiency curve
50% Load		95		%	See Figure 1 for efficiency curve



Current: 10A

MCOTS-C-28-50-HZ ELECTRICAL CHARACTERISTICS

Ta = 25 °C, Vin = 28dc unless otherwise noted; full operating temperature range is -55 °C to +100 °C baseplate temperature with appropriate power derating. Specifications subject to change without notice.

DYNAMIC CHARACTERISTICSTurn-On Tiransient243540msFull load, Vout=90% nom.Output Voltage Overshoot2%No Load, 1mF load capSolation Voltage (dielectric strength)2250VIsolation Resistance30MΩIsolation Capacitance (input to output)1000pFSee Note 4TEMPERATURE LIMITS FOR POWER DERATING CURVES125°CPackage rated to 150 °CSemiconductor Junction Temperature125°CUL rated max operating temp 130 °CBoard Temperature125°CUL rated max operating temp 130 °CTransformer Temperature100°CFEATURE CHARACTERISTICSSwitching Frequency230240250KHzOff-State Voltage2.418.0VOff-State Voltage-2.00.8VON/OFF Control1518VPull-Up Voltage1518VPull-Up Voltage50kQOver-Temperature Shutdown OTP Trip Point120°CVer-Temperature Shutdown Restart Hysteresis10°CCalculated MTBF per MIL-HDBK-217F (GB)4.110· Hrs.Tb = 70 °CCalculated MTBF per MIL-HDBK-217F (GM)0.9210· Hrs.Tb = 70 °C	Parameter	Min.	Тур.	Max.	Units	Notes & Conditions
Turn-On Time243540msFull load, Vout=90% nom. No Load, 1mF load capOutput Voltage Qvershoot2%No Load, 1mF load capISOLATION CHARACTERISTICSIsolation Voltage (dielectric strength)2250VIsolation Resistance30MΩIsolation Capacitance (input to output)1000pFSemiconductor Junction Temperature125°CBoard Temperature125°CBoard Temperature125°CBoard Temperature125°CWaitching Frequency230240ON/OFF Control0°COff-State Voltage2.418.0OV/OFF ControlPull-Up Voltage1518VPull-Up Resistance50KLQOver-Temperature Shutdown OTP Trip Point120°CAverage PCB Temperature120°CReliabilitity CHARACTERISTICS-Switching Frequency0.8VOV/OFF ControlOW-OFF Exter Voltage-2.00.8Over-Temperature Shutdown OTP Trip Point120°COver-Temperature Shutdown Restart Hysteresis10°CCalculated MTBF per MIL-HDBK-217F (GB)4.110° Hrs.Calculated MTBF per MIL-HDBK-217F (GM)0.9210° Hrs.	DYNAMIC CHARACTERISTICS					
Output Voltage Overshoot2%No Load, 1mF load capISOLATION CHARACTERISTICSIsolation Voltage (dielectric strength)2250VIsolation Resistance30MQIsolation Capacitance (input to output)1000pFSemiconductor Junction Temperature1000pFBoard Temperature125°CBoard Temperature125°CBoard Temperature125°CTransformer Temperature, Tb1000°CFEATURE CHARACTERISTICS1000°CSwitching Frequency230240ON/OFF Control230240Off-State Voltage2.418.0OV/OFF Control100°CPull-Up Voltage1518Pull-Up Resistance50kQOver-Temperature Shutdown OTP Trip Point120°CAverage PCB Temperature10°CReLIABILITY CHARACTERISTICS10°CCalculated MTBF per MIL-HDBK-217F (GB)4.110 Hrs.Tb = 70 °C10 Hrs.Tb = 70 °C	Turn-On Transient					
ISOLATION CHARACTERISTICS Isolation Voltage (dielectric strength) 2250 V Isolation Resistance 30 MQ Isolation Capacitance (input to output) 1000 pF Semiconductor Junction Temperature 125 °C Board Temperature 125 °C Image: Transformer Temperature 125 °C Maximum Baseplate Temperature, Tb 100 °C FEATURE CHARACTERISTICS 230 240 250 Switching Frequency 230 240 250 ON/OFF Control 0 °C ON/OFF Control 0 °C Pull-Up Voltage -2.0 0.8 V ON/OFF Control 0 °C °C Pull-Up Voltage 15 18 V Pull-Up Resistance 50 kΩ °C Over-Temperature Shutdown OTP Trip Point 120 °C Average PCB Temperature Over-Temperature Shutdown Restart Hysteresis 10 °C C RELIABILITY CHARACTERISTICS Calculated MTBF per MIL-HDBK-217F (GB) 4.1 10 ^e Hrs. Tb = 70 °C	Turn-On Time	24	35	40	ms	Full load, Vout=90% nom.
Isolation Voltage (dielectric strength)2250VIsolation Resistance30MΩIsolation Capacitance (input to output)1000pFSemiconductor Junction Temperature125°CBoard Temperature125°CBoard Temperature125°CBoard Temperature125°CWaximum Baseplate Temperature, Tb100°CFEATURE CHARACTERISTICSSwitching Frequency230240250ON/OFF ControlOff-State Voltage2.418.0VOn-State Voltage-2.00.8VPull-Up Voltage1518VPull-Up Resistance50kQ2Over-Temperature Shutdown OTP Trip Point120°CAverage PCB Temperature50kQ2Over-Temperature Shutdown Restart Hysteresis10°CRELIABILITY CHARACTERISTICSCalculated MTBF per MIL-HDBK-217F (GB)4.110· Hrs.The 70 °C10· Hrs.Tb = 70 °C	Output Voltage Overshoot			2	%	No Load, 1mF load cap
Isolation Resistance30MΩIsolation Capacitance (input to output)1000pFSee Note 4TEMPERATURE LIMITS FOR POWER DERATING CURVES125°CPackage rated to 150 °CSemiconductor Junction Temperature125°CUL rated max operating temp 130 °CBoard Temperature125°CUL rated max operating temp 130 °CTransformer Temperature125°CUL rated max operating temp 130 °CMaximum Baseplate Temperature, Tb100°CFEATURE CHARACTERISTICS100°CSwitching Frequency230240250kHzON/OFF Control000Off-State Voltage2.418.0VON/OFF Control000Pull-Up Voltage1518VPull-Up Resistance50KΩAverage PCB TemperatureOver-Temperature Shutdown OTP Trip Point120°CAverage PCB TemperatureOver-Temperature Shutdown Restart Hysteresis10°CCRELLARICT CHARACTERISTICS10° Hrs.Tb = 70 °CCalculated MTBF per MIL-HDBK-217F (GB)0.9210° Hrs.Tb = 70 °C	ISOLATION CHARACTERISTICS					
Isolation Capacitance (input to output)1000pFSee Note 4TEMPERATURE LIMITS FOR POWER DERATING CURVESSemiconductor Junction Temperature125°CPackage rated to 150 °CBoard Temperature125°CUL rated max operating temp 130 °CTransformer Temperature125°CUL rated max operating temp 130 °CTransformer Temperature, Tb100°CFEATURE CHARACTERISTICS100°CSwitching Frequency230240250kHzON/OFF Control230240250kHzOff-State Voltage2.418.0VON/OFF Control00.8VPull-Up Voltage1518VPull-Up Resistance50kΩOver-Temperature Shutdown OTP Trip Point120°COver-Temperature Shutdown Restart Hysteresis10°CRELLABILITY CHARACTERISTICS10° Hrs.Tb = 70 °CCalculated MTBF per MIL-HDBK-217F (GB)4.110° Hrs.Tb = 70 °C	Isolation Voltage (dielectric strength)		2250		V	
TEMPERATURE LIMIT'S FOR POWER DERATING CURVESSemiconductor Junction Temperature125°CPackage rated to 150 °CBoard Temperature125°CUL rated max operating temp 130 °CTransformer Temperature125°CUL rated max operating temp 130 °CMaximum Baseplate Temperature, Tb100°CFEATURE CHARACTERISTICS100°CSwitching Frequency230240250kHzON/OFF Control240250kHzIsolation stage switching freq. is half thisON/OFF Control00.8VON/OFF Control1518VPull-Up Voltage1518VPull-Up Resistance50kQOver-Temperature Shutdown OTP Trip Point120°COver-Temperature Shutdown Restart Hysteresis10°CRELIABILITY CHARACTERISTICS4.110° Hrs.Tb = 70 °CCalculated MTBF per MIL-HDBK-217F (GB)4.110° Hrs.Tb = 70 °C	Isolation Resistance		30		MΩ	
Semiconductor Junction Temperature125°CPackage rated to 150 °CBoard Temperature125°CUL rated max operating temp 130 °CTransformer Temperature125°CUL rated max operating temp 130 °CMaximum Baseplate Temperature, Tb100°CFEATURE CHARACTERISTICS100°CSwitching Frequency230240250kHzON/OFF Control230240250kHzOn-State Voltage2.418.0VON/OFF Control-2.00.8VPull-Up Voltage1518VPull-Up Resistance50kΩAverage PCB TemperatureOver-Temperature Shutdown OTP Trip Point120°CAverage PCB TemperatureOver-Temperature Shutdown Restart Hysteresis10°CRELIABILITY CHARACTERISTICS4.110° Hrs.Tb = 70 °CCalculated MTBF per MIL-HDBK-217F (GB)4.110° Hrs.Tb = 70 °C	Isolation Capacitance (input to output)		1000		pF	See Note 4
Board Temperature125°CUL rated max operating temp 130 °CTransformer Temperature125°C125°CMaximum Baseplate Temperature, Tb100°C°CFEATURE CHARACTERISTICSSwitching Frequency230240250kHzIsolation stage switching freq. is half thisON/OFF Control2.418.0VVOn-State Voltage-2.00.8VVON/OFF Control-2.00.8VOW/OFF Control-50kΩVPull-Up Resistance50kΩOver-Temperature Shutdown OTP Trip Point120°COver-Temperature Shutdown Restart Hysteresis10°CRELTABILITY CHARACTERISTICS4.110° Hrs.Tb = 70 °CCalculated MTBF per MIL-HDBK-217F (GB)4.110° Hrs.Tb = 70 °CCalculated MTBF per MIL-HDBK-217F (GM)0.9210° Hrs.Tb = 70 °C	TEMPERATURE LIMITS FOR POWER DERATI	NG CURVES				
Transformer Temperature125°COr react man operating tamp for the formation of the formation man operating tamp for the formation formation man operating tamp for the formation formation formation for the formation formation formation for the formation for the formation for the formation	Semiconductor Junction Temperature			125	-	Package rated to 150 °C
Maximum Baseplate Temperature, Tb100°CFEATURE CHARACTERISTICS300240250kHzIsolation stage switching freq. is half thisSwitching Frequency230240250kHzIsolation stage switching freq. is half thisON/OFF Control00000Off-State Voltage2.418.0VOn-State Voltage-2.00.8VON/OFF Control0000Pull-Up Voltage1518VPull-Up Resistance50kΩOver-Temperature Shutdown OTP Trip Point120°COver-Temperature Shutdown Restart Hysteresis10°CRELIABILITY CHARACTERISTICS4.110° Hrs.Tb = 70 °CCalculated MTBF per MIL-HDBK-217F (GB)4.110° Hrs.Tb = 70 °CCalculated MTBF per MIL-HDBK-217F (GM)0.9210° Hrs.Tb = 70 °C	Board Temperature			125	°C	UL rated max operating temp 130 °C
FEATURE CHARACTERISTICSSwitching Frequency230240250kHzIsolation stage switching freq. is half thisON/OFF Control2.418.0VOn-State Voltage-2.00.8VON/OFF Control-2.00.8VON/OFF Control-2.00.8VON/OFF Control-2.00.8VPull-Up Voltage1518VPull-Up Resistance50kΩOver-Temperature Shutdown OTP Trip Point120°COver-Temperature Shutdown Restart Hysteresis10°CRELIABILITY CHARACTERISTICS4.110° Hrs.Tb = 70 °CCalculated MTBF per MIL-HDBK-217F (GB)4.110° Hrs.Tb = 70 °CCalculated MTBF per MIL-HDBK-217F (GM)0.9210° Hrs.Tb = 70 °C	Transformer Temperature			125	°C	
Switching Frequency230240250kHzIsolation stage switching freq. is half thisON/OFF ControlOff-State Voltage2.418.0VOn-State Voltage-2.00.8VON/OFF ControlPull-Up Voltage1518VPull-Up Resistance50-kΩOver-Temperature Shutdown OTP Trip Point120°CAverage PCB Temperature-Over-Temperature Shutdown Restart Hysteresis10°CRELIABILITY CHARACTERISTICS4.110° Hrs.Tb = 70 °CCalculated MTBF per MIL-HDBK-217F (GB)4.110° Hrs.Tb = 70 °CCalculated MTBF per MIL-HDBK-217F (GM)0.9210° Hrs.Tb = 70 °C	Maximum Baseplate Temperature, Tb			100	°C	
ON/OFF ControlImage: Control off-State VoltageImage: Control off-State Voltage<	FEATURE CHARACTERISTICS					
Off-State Voltage2.418.0VOn-State Voltage-2.00.8VON/OFF Control-2.00.8VPull-Up Voltage1518VPull-Up Resistance50 $k\Omega$ Over-Temperature Shutdown OTP Trip Point120°COver-Temperature Shutdown Restart Hysteresis10°CRELIABILITY CHARACTERISTICS		230	240	250	kHz	Isolation stage switching freq. is half this
On-State Voltage -2.0 0.8 V ON/OFF Control -2.0 0.8 V Pull-Up Voltage 15 18 V Pull-Up Resistance 50 kΩ Over-Temperature Shutdown OTP Trip Point 120 °C Average PCB Temperature Over-Temperature Shutdown Restart Hysteresis 10 °C RELIABILITY CHARACTERISTICS Calculated MTBF per MIL-HDBK-217F (GB) 4.1 10° Hrs. Tb = 70 °C Calculated MTBF per MIL-HDBK-217F (GM) 0.92 10° Hrs. Tb = 70 °C	ON/OFF Control					
ON/OFF Control Ind Ind Ind Pull-Up Voltage 15 18 V Pull-Up Resistance 50 kΩ Over-Temperature Shutdown OTP Trip Point 120 °C Over-Temperature Shutdown Restart Hysteresis 10 °C RELIABILITY CHARACTERISTICS Ind Host Calculated MTBF per MIL-HDBK-217F (GB) 4.1 10° Hrs. Tb = 70 °C Calculated MTBF per MIL-HDBK-217F (GM) 0.92 10° Hrs. Tb = 70 °C						
Pull-Up Voltage1518VPull-Up Resistance50 $k\Omega$ Over-Temperature Shutdown OTP Trip Point120°COver-Temperature Shutdown Restart Hysteresis10°CRELIABILITY CHARACTERISTICSCalculated MTBF per MIL-HDBK-217F (GB)4.110° Hrs.Calculated MTBF per MIL-HDBK-217F (GM)0.9210° Hrs.	On-State Voltage	-2.0		0.8	V	
Pull-Up Resistance 50 kΩ Over-Temperature Shutdown OTP Trip Point 120 °C Average PCB Temperature Over-Temperature Shutdown Restart Hysteresis 10 °C Reliability CHARACTERISTICS Calculated MTBF per MIL-HDBK-217F (GB) 4.1 10° Hrs. Tb = 70 °C Calculated MTBF per MIL-HDBK-217F (GM) 0.92 10° Hrs. Tb = 70 °C	ON/OFF Control					
Over-Temperature Shutdown OTP Trip Point120°CAverage PCB TemperatureOver-Temperature Shutdown Restart Hysteresis10°CRELIABILITY CHARACTERISTICSCalculated MTBF per MIL-HDBK-217F (GB)4.110° Hrs.Tb = 70 °CCalculated MTBF per MIL-HDBK-217F (GM)0.9210° Hrs.Tb = 70 °C	Pull-Up Voltage		15	18	V	
Over-Temperature Shutdown Restart Hysteresis 10 °C RELIABILITY CHARACTERISTICS 10 Indext Pressure Calculated MTBF per MIL-HDBK-217F (GB) 4.1 10° Hrs. Tb = 70 °C Calculated MTBF per MIL-HDBK-217F (GM) 0.92 10° Hrs. Tb = 70 °C	Pull-Up Resistance		50		kΩ	
RELIABILITY CHARACTERISTICS Calculated MTBF per MIL-HDBK-217F (GB) 4.1 10° Hrs. Tb = 70 °C Calculated MTBF per MIL-HDBK-217F (GM) 0.92 10° Hrs. Tb = 70 °C	Over-Temperature Shutdown OTP Trip Point		120		°C	Average PCB Temperature
Calculated MTBF per MIL-HDBK-217F (GB) 4.1 10 ⁶ Hrs. Tb = 70 °C Calculated MTBF per MIL-HDBK-217F (GM) 0.92 10 ⁶ Hrs. Tb = 70 °C	Over-Temperature Shutdown Restart Hysteresis		10		°C	
Calculated MTBF per MIL-HDBK-217F (GM) 0.92 10 ⁶ Hrs. Tb = 70 °C	RELIABILITY CHARACTERISTICS					
	Calculated MTBF per MIL-HDBK-217F (GB)		4.1		10º Hrs.	Tb = 70 °C
	Calculated MTBF per MIL-HDBK-217F (GM)		0.92		10º Hrs.	Tb = 70 °C
Field Demonstrated MTBF	Field Demonstrated MTBF				10 ⁶ Hrs.	See our website for details

Note 1: Line and load regulation is limited by duty cycle quantization and does not indicate a shift in the internal voltage reference.

Note 2: For applications requiring reduced output voltage ripple and noise, consult SynQor applications support (e-mail: support@synqor.com).

Note 3: If the output voltage falls below the Output DC Current Limit Shutdown Voltage for more than 50ms, then the unit will enter into hiccup mode, with a 500ms off-time.

Note 4: Higher values of isolation capacitance can be added external to the module.

STANDARDS COMPLIANCE

Parameter	Notes & Conditions	
STANDARDS COMPLIANCE	Pending	
UL 62368-1	Basic Insulation	
CAN/CSA-C22.2 No. 62368-1		
EN 62368		

Note: An external input fuse must always be used to meet these safety requirements. Contact SynQor for official safety certificates on new releases or

16 ,

Current: 10A

Technical Specification

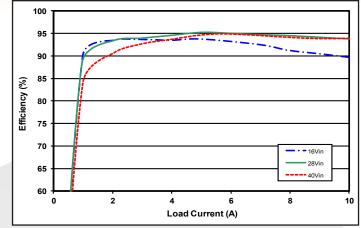


Figure 1: Efficiency, at nominal output voltage vs. load current for minimum, nominal, and maximum input voltages at 25 °C.

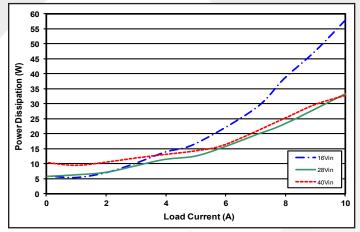


Figure 3: Power Dissipation, at nominal output voltage vs. load current for minimum, nominal, and maximum input voltages at 25 °C.

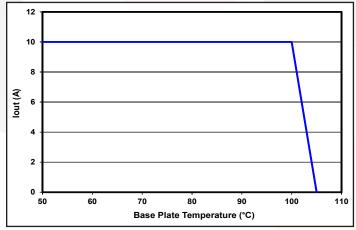


Figure 5: Thermal Derating, (maximum output current vs. base plate temperature) at nominal input voltage.

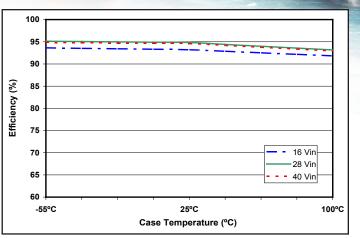


Figure 2: Efficiency, at nominal output voltage and 60% rated power vs. case temperature for minimum, nominal, and maximum input voltages.

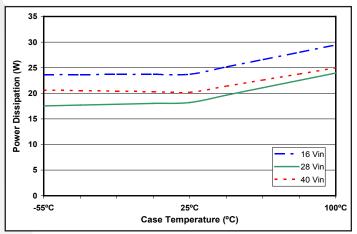


Figure 4: Power Dissipation, at nominal output voltage and 60% rated power vs. case temperature for minimum, nominal, and maximum input voltages.

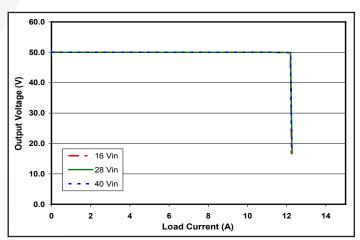
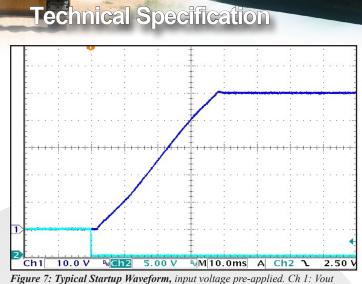
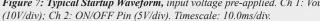


Figure 6: Output I-V Characteristics, (output voltage vs. load current) showing typical current limit curves. See Current Limit section in the Application Notes.





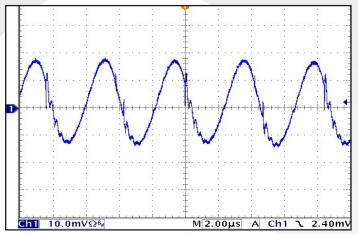


Figure 9: Input Terminal Current Ripple, *i*_C at full rated output current and nominal input voltage with SynQor MCOTS filter module (200 mA/div). Bandwidth: 20 MHz. Timescale: 2.00µs/div. See Figure 13.

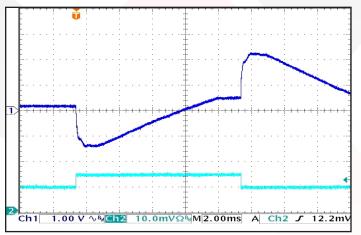


Figure 11: Output Voltage Response to Step-Change in Load Current, (50%-75%-50% of lout(max); $dl/dt = 5 A/\mu s$). Load capacitance: $1 \mu F$ ceramic and 100 μF electrolytic capacitors. Ch 1: Vout (lV/div); Ch 2: lout (5A/div). Timescale: 2.00ms/div.

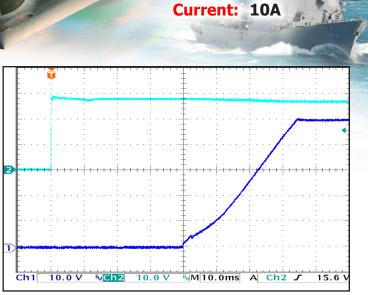


Figure 8: Turn-On Transient, at full resistive load and zero output capacitance, initiated by Vin. Ch 1: Vout (10V/div); Ch 2: Vin (10V/div). Timescale: 10.0ms/ div.

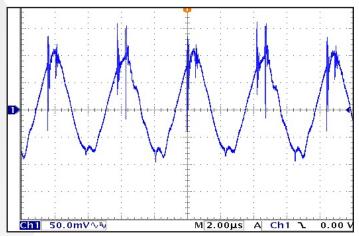


Figure 10: Output Voltage Ripple, Vout, at nominal input voltage and rated load current (50 mV/div). Load capacitance: $1 \mu F$ ceramic and $10 \mu F$ tantalum capacitors. Bandwidth: 10 MHz. Timescale: 2.00 μ sec/div. See Figure 13.

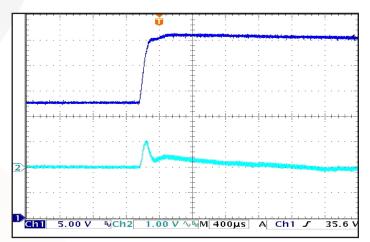
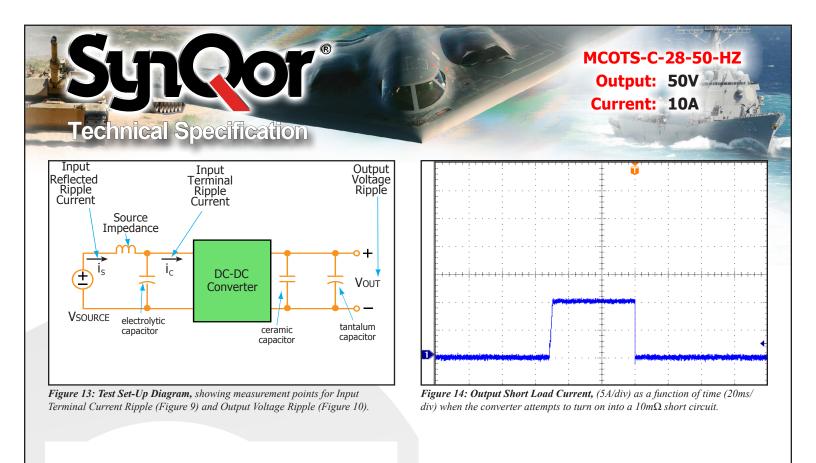


Figure 12: Output Voltage Response to Step-Change in Input Voltage, (dV/dt = 250V/ms). Load capacitance: 330 µF electrolytic output capacitance. Ch 1: Vin (5V/div); Ch 2: Vout (1V/div). Timescale: 400µs/div.





BASIC OPERATION AND FEATURES

This converter series uses a two-stage power conversion topology. The first stage keeps the output voltage constant over variations in line, load, and temperature. The second stage uses a transformer to provide the functions of input/output isolation and voltage stepdown to achieve the low output voltage required.

Both the first stage and the second stage switch at a fixed frequency for predictable EMI performance. Rectification of the transformer's output is accomplished with synchronous rectifiers. These devices, which are MOSFETs with a very low on-state resistance, dissipate significantly less energy than Schottky diodes, enabling the converter to achieve high efficiency.

Dissipation throughout the converter is so low that it does not require a heatsink for operation in many applications; however, adding a heatsink provides improved thermal derating performance in extreme situations. To further withstand harsh environments and thermally demanding applications, the converter is available totally encased. See Ordering Information page for available thermal design options.

SynQor half-brick converters use the industry standard footprint and pin-out.

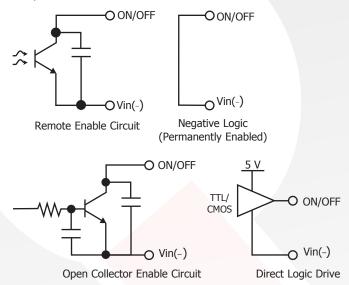
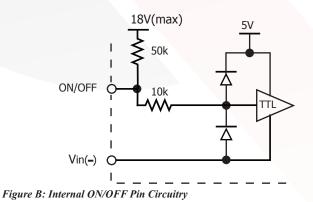


Figure A: Various Circuits for Driving the ON/OFF Pin



CONTROL FEATURES

REMOTE ON/OFF (Pin 2): The ON/OFF input, Pin 2, permits the user to control when the converter is on or off. This input is referenced to the return terminal of the input bus, Vin(-).

In the negative logic version, the ON/OFF signal is active low (meaning that a low voltage turns the converter on). Figure A details possible circuits for driving the ON/OFF pin. Figure B is a detailed look of the internal ON/OFF circuitry.

REMOTE SENSE Pins 8(+) and 6(-): The SENSE(+) and SENSE(-) inputs correct for voltage drops along the conductors that connect the converter's output pins to the load.

Pin 8 should be connected to Vout(+) and Pin 6 should be connected to Vout(-) at the point on the board where regulation is desired. If these connections are not made, the converter will deliver an output voltage that is slightly higher than its specified value.

Note: The Output Over-Voltage Protection circuit senses the voltage across the output (Pins 9 and 5) to determine when it should trigger, not the voltage across the converter's sense leads (Pins 8 and 6). Therefore, the resistive drop on the board should be small enough so that output OVP does not trigger, even during load transients.

OUTPUT VOLTAGE TRIM (Pin 7): The TRIM input permits the user to adjust the output voltage across the sense leads up or down according to the trim range specifications. SynQor uses industry standard trim equations.

To decrease the output voltage, the user should connect a resistor between Pin 7 (TRIM) and Pin 6 (SENSE(-) input). For a desired decrease of the nominal output voltage, the value of the resistor should be:

Rtrim-down = $\left(\frac{100\%}{\Delta\%} - 2\right) k\Omega$

where

$$\Delta\% = \left| \frac{\text{Vnominal} - \text{Vdesired}}{\text{Vnominal}} \right| \times 100\%$$

To increase the output voltage, the user should connect a resistor between Pin 7 (TRIM) and Pin 8 (SENSE(+) input). For a desired increase of the nominal output voltage, the value of the resistor should be:

Rtrim-up =
$$\frac{\left(\frac{\text{Vnominal}}{1.225} - 2\right) \times \text{Vdesired} + \text{Vnominal}}{\text{Vdesired} - \text{Vnominal}} k\Omega$$

MCOTS-C-28-50-HZ

MCOTS-C-28-50-HZ Output: 50V Current: 10A



The Trim Graph in Figure C shows the relationship between the trim resistor value and Rtrim-up and Rtrim-down, showing the total range the output voltage can be trimmed up or down.

Note: The TRIM feature does not affect the voltage at which the output over-voltage protection circuit is triggered. Trimming the output voltage too high may cause the over-voltage protection circuit to engage, particularly during transients.

It is not necessary for the user to add capacitance at the TRIM pin. The node is internally filtered to eliminate noise.

Total DC Variation of Vout: For the converter to meet its full specifications, the maximum variation of the DC value of Vout, due to both trimming and remote load voltage drops, should not be greater than that specified for the output voltage trim range.

Active Trimming: Active trimming of the output voltage is supported, but dynamic active trimming with feedback is discouraged due to the potential for limit-cycling. If such trimming is necessary, control loop bandwidth should be limited to <1 Hz. A deadband which is at least as large as the line/load regulation specification is also recommended, but not required.

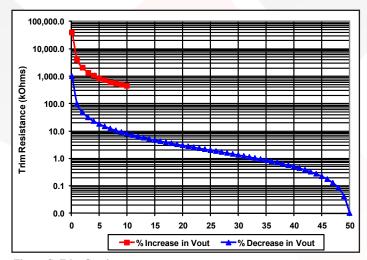


Figure C: Trim Graph

Protection Features

Input Under-Voltage Lockout (UVLO): The converter is designed to turn off when the input voltage is too low, helping to avoid an input system instability problem, which is described in more detail in the application note titled "Input System Instability" on the SynQor website. The lockout circuitry is a comparator with DC hysteresis. When the input voltage is rising, it must exceed the typical "Turn-On Voltage Threshold" value* before the converter will turn on. Once the converter is on, the input voltage must fall below the typical Turn-Off Voltage Threshold value before the converter will turn off.

Output Current Limit (OCP): If the output current exceeds the "Output DC Current Limit Inception" value*, then a fast linear current limit controller will reduce the output voltage to maintain a constant output current. If as a result, the output voltage falls below the "Output DC Current Limit Shutdown Voltage"* for more than 50 ms**, then the unit will enter into hiccup mode, with a 500 ms off-time. The unit will then automatically attempt to restart.

Back-Drive Current Limit: If there is negative output current of a magnitude larger than the "Back-Drive Current Limit while Enabled" specification*, then a fast back-drive limit controller will increase the output voltage to maintain a constant output current. If this results in the output voltage exceeding the "Output Over-Voltage Protection" threshold*, then the unit will shut down.

Output Over-Voltage Limit (OVP): If the voltage across the output pins exceeds the Output Over-Voltage Protection threshold, the converter will immediately stop switching. This prevents damage to the load circuit due to 1) excessive series resistance in output current path from converter output pins to sense point, 2) a release of a short-circuit condition, or 3) a release of a current limit condition. Load capacitance determines exactly how high the output voltage will rise in response to these conditions. After 500 ms the converter will automatically restart.

Over-Temperature Shutdown (OTP): A temperature sensor on the converter senses the average temperature of the module. The thermal shutdown circuit is designed to turn the converter off when the temperature at the sensed location reaches the "Over-Temperature Shutdown" value*. It will allow the converter to turn on again when the temperature of the sensed location falls by the amount of the "Over-Temperature Shutdown Restart Hysteresis" value*.

Startup Inhibit Period: The Startup Inhibit Period ensures that the converter will remain off for approximately 500 ms when it is shut down due to a fault. This generates a 2 Hz "hiccup mode," which prevents the converter from overheating. There are multiple ways that the converter can be shut down, initiating a Startup Inhibit Period:

- Output Over-Voltage Protection
- Current Limit
- Short Circuit Protection

* See Electrical Characteristics section.

** Certain models may have an extended on-time, longer than 50 ms. See Electrical Characteristics section.



APPLICATION CONSIDERATIONS

Input System Instability: This condition can occur because any DC-DC converter appears incrementally as a negative resistance load. A detailed application note titled "Input System Instability" is available on the SynQor website which provides an understanding of why this instability arises, and shows the preferred solution for correcting it.

Application Circuits: A typical circuit diagram, Figure D below details the input filtering and voltage trimming.

Input Filtering and External Input Capacitance: Figure E below shows the internal input filter components. This filter dramatically reduces input terminal ripple current, which otherwise could exceed the rating of an external electrolytic input capacitor. The recommended external input capacitance is specified in the Input Characteristics section of the Electrical Specifications. More detailed information is available in the application note titled "EMI Characteristics" on the SynQor website.

Output Filtering and External Output Capacitance: The internal output filter components are shown in Figure E below. This filter dramatically reduces output voltage ripple. Some minimum external output capacitance is required, as specified in the Output Characteristics area of the Electrical Characteristics section. No damage will occur without this capacitor connected, but peak output voltage ripple will be much higher.

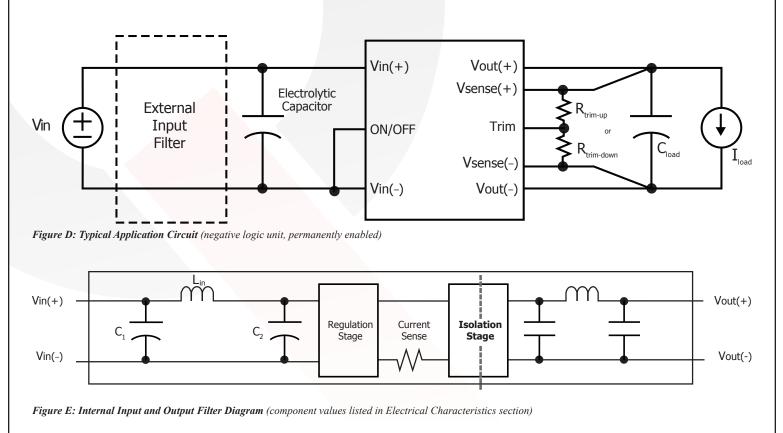
Thermal Considerations: For baseplated and encased versions, the max operating baseplate temperature, TB, is 100 °C. Refer to the Thermal Derating Curves in the Technical Figures section to see the available output current at baseplate temperatures below 100 °C.

A power derating curve can be calculated for any heatsink that is attached to the base-plate of the converter. It is only necessary to determine the thermal resistance, RTHBA, of the chosen heatsink between the baseplate and the ambient air for a given airflow rate. This information is usually available from the heatsink vendor. The following formula can the be used to determine the maximum power the converter can dissipate for a given thermal condition if its base-plate is to be no higher than 100 °C.

$$P_{diss}^{max} = \frac{100 \text{ °C} - TA}{RTHBA}$$

This value of maximum power dissipation can then be used in conjunction with the data shown in the Power Dissipation Curves in the Technical Figures section to determine the maximum load current (and power) that the converter can deliver in the given thermal condition.

For convenience, Thermal Derating Curves are provided in the Technical Figures section.





Active Current Share Application Section

Overview: The full-featured option, which is specified by an "F" as the last character of the part number, supports current sharing by adding two additional pins: SHARE(+) and SHARE(-)

Connection of Paralleled Units: Up to 100 units can be placed in parallel. In this current share architecture, one unit is dynamically chosen to act as a master, controlling all other units. It cannot be predicted which unit will become the master at any given time, so units should be wired symmetrically (see Figures F & G).

- Input power pins and output power pins should be tied together between units, preferably with wide overlapping copper planes, after any input common-mode choke.
- The SHARE(+) and SHARE(-) pins should be routed between all paralleled units as a differential pair.
- The ON/OFF pins should be connected in parallel, and rise/fall times should be kept below 2 ms.
- The SENSE(+) and SENSE(-) pins should be connected either locally at each unit or separately to a common sense point. If an output common-mode choke is used, sense lines should be connected on the module-side of the choke.
- If the TRIM pin is used, then each unit should have its own trim resistor connected locally between TRIM and SENSE(+) or SENSE(-).

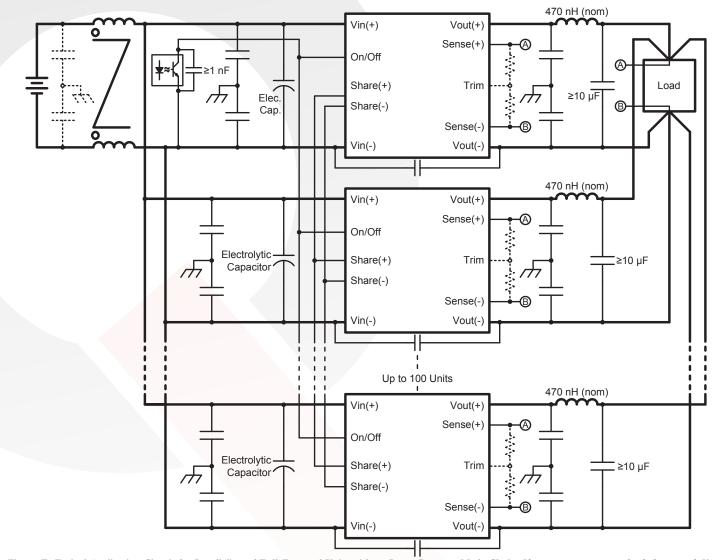


Figure F: Typical Application Circuit for Paralleling of Full-Featured Units with an Input Common-Mode Choke. If an input common-mode choke is used, Vin(-) MUST be tied together AFTER the choke for all units. 470 nH (nominal) inductor or an output common-mode choke is required for outputs >18 V. See Figure G for output common-mode choke configuration.

MCOTS-C-28-50-HZ Output: 50V Current: 10A

Technical Specification

Automatic Configuration: The micro-controller inside each power converter unit is programmed at the factory with a unique chip number. In every other respect, each shared unit is identical and has the same orderable part number.

On initial startup (or after the master is disabled or shuts down), each unit determines the chip number of every other unit currently connected to the shared serial bus formed by the SHARE(+) and SHARE(-) pins. The unit with the highest chip number dynamically reconfigures itself from slave to master. The rest of the units (that do not have the highest chip number) become slaves.

The master unit then broadcasts its control state over the shared serial bus on a cycle-by-cycle basis. The slave units interpret and implement the control commands sent by the master, mirroring every action of the master unit.

If the master is disabled or encounters a fault condition, all units will immediately shut down, and if the master unit is unable to restart, then the unit with the next highest chip number will become master. If a slave unit is disabled or encounters a fault condition, all other units continue to run, and the slave unit can restart seamlessly.

Automatic Interleaving: The slave units automatically lock frequency with the master, and interleave the phase of their switching transitions for improved EMI performance. To obtain the phase angle relative to the master, each slave divides 360 degrees by the total number of connected units, and multiples the result by its rank among chip numbers of connected units.

ORing Diodes placed in series with the converter outputs must also have a resistor smaller than 500 Ω placed in parallel. This resistor keeps the output voltage of a temporarily disabled slave unit consistent with the active master unit. If the output voltage of the slave unit were allowed to totally discharge, and the slave unit tried to restart, it would fail because the slave reproduces the duty cycle of the master unit, which is running in steady state and cannot repeat an output voltage soft-start.

Common-Mode Filtering must be either a single primary side choke handling the inputs from all the paralleled units, or multiple chokes placed on the secondary side. This ensures that a solid Vin(-) plane is maintained between units. Adding a common-mode choke at the output eliminates the need for the 470 nH indcutor at the output of shared units when Vout > 18 V. If an output common-mode choke is used, sense connections must be made on the module-side of the choke.

Resonance Between Output Capacitors is Possible: When multiple higher-voltage modules are paralleled, it is possible to excite a series resonance between the output capacitors internal to the module and the parasitic inductance of the module output pins. This is especially likely at higher output voltages where the module internal capacitance is relatively small. This problem is independent of external output capacitance. For modules with an output voltage greater than 18 V, to ensure that this resonant frequency is below the switching frequency it is recommended to add a nominal 470 nH of inductance, located close to the module, in series with each converter output. There must be at least 10 µF of capacitance per converter, located on the load-side of that inductor. The inductance could be from the leakage inductance of a secondary-side common-mode choke; in which case the output capacitor should be appropriately sized for the chosen choke. When using an output common-mode choke, the Sense lines must be connected on the module-side of the common-mode choke (see Figure G).

RS-485 Physical Layer: The internal RS-485 transceiver includes many advanced protection features for enhanced reliability:

- Current Limiting and Thermal Shutdown for Driver Overload Protection
- IEC61000 ESD Protection to +/- 16.5 kV
- Hot Plug Circuitry SHARE(+) and SHARE(-) Outputs Remain Tri-State During Power-up/Power-down

Internal Schottky Diode Termination: Despite signaling at high speed with fast edges, external termination resistors are not necessary. Each receiver has four Schottky diodes built in, two for each line in the differential pair. These diodes clamp any ringing caused by transmission line reflections, preventing the voltage from going above about 5.5 V or below about -0.5 V. Any subsequent ringing then inherently takes place between 4.5 and 5.5 V or between -0.5 and 0.5 V. Since each receiver on the bus contains a set of clamping diodes to clamp any possible transmission line reflection, the bus does not necessarily need to be routed as a daisy-chain.

Pins SHARE(+) and SHARE(-) are referenced to Vin(-), and therefore should be routed as a differential pair near the Vin(-) plane for optimal signal integrity. The maximum difference in voltage between Vin(-) pins of all units on the share-bus should be kept within 0.3 V to prevent steady-state conduction of the termination diodes. Therefore, the Vin(-) connections to each unit must be common, preferably connected by a single copper plane.

Share Accuracy: Inside each converter micro-controller, the duty cycle is generated digitally, making for excellent duty cycle matching between connected units. Some small duty cycle mismatch is caused by (well controlled) process variations in the MOSFET gate drivers. However, the voltage difference induced by this duty cycle mismatch appears across the impedance of the entire power converter, from input to output, multiplied by two, since the differential current flows out of one converter and into another. So, a small duty cycle mismatch yields very small differential currents, which remain small even when 100 units are placed in parallel.

In other current-sharing schemes, it is common to have a current-sharing control loop in each unit. However, due to the limited bandwidth of this loop, units do not necessarily share current on startup or during transients before this loop has a chance to respond. In contrast, the current-sharing scheme used in this product has no control dynamics: control signals are transmitted fast enough that the slave units can mirror the control state of the master unit on a cycle-by-cycle basis, and the current simply shares properly, from the first switching cycle to the last.

Technical Specification

R



Mi , 143

Current: 10A

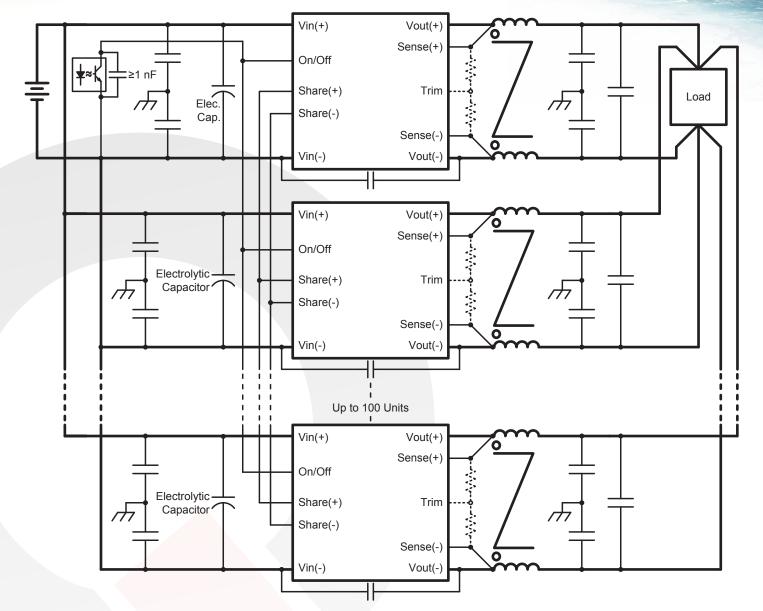
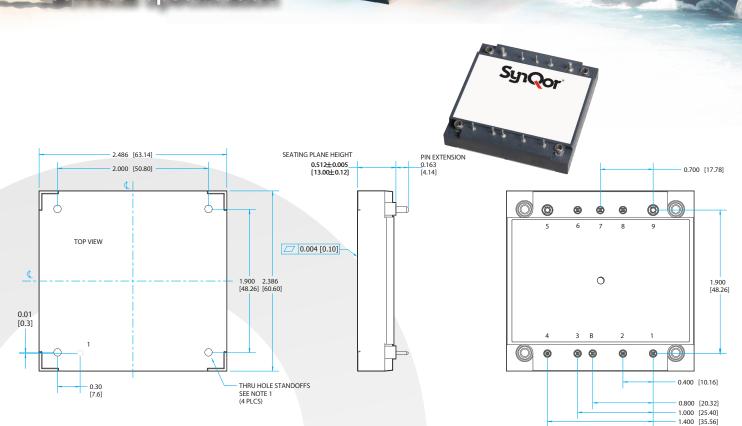


Figure G: Typical Application Circuit for Paralleling of Full-Featured Units with an Output Common-Mode Choke. When using an output common-mode choke, SENSE lines must be connected on the module-side of the choke. See Figure F for configuration with an input common-mode choke.

Current: 10A

Technical Specification



R

NOTES

1) THREADED: APPLIED TORQUE PER M3 SCREW NOT TO EXCEED 6 in-lb (0.7 Nm).

NONTHREADED: DIA 0.125" (3.18 mm)

- 2) BASEPLATE FLATNESS TOLERANCE IS 0.004" (0.10 mm) TIR FOR SURFACE.
- 3) PINS 1-4, B AND 6-8 ARE 0.040" (1.02 mm) DIA. WITH 0.080" (2.03 mm) DIA. STANDOFFS.
- 4) PINS 5 AND 9 ARE 0.080" (2.03 mm) DIA. WITH 0.125" (3.18 mm) DIA STANDOFFS
- 5) ALL PINS: MATERIAL: COPPER ALLOY FINISH: MATTE TIN OVER NICKEL PLATE
- 6) WEIGHT: 5.2 oz. (146 g)
- ALL DIMENSIONS IN INCHES (mm) TOLERANCES: X.XX IN +/-0.02 (X.X mm +/-0.5 mm) X.XXX IN +/-0.010 (X.XX mm +/-0.25 mm)

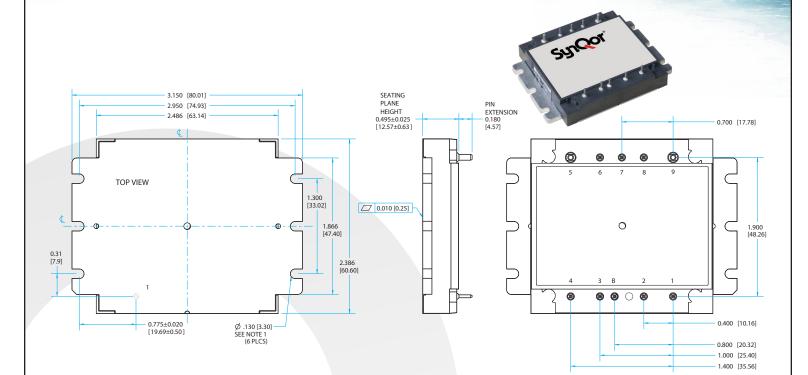
PIN DESIGNATIONS

Pin	Name	Label	Function			
1	Vin(+)	+VIN	Positive input voltage			
2	ON/OFF	ON/OFF	TTL input to turn converter on and off, referenced to Vin(–), with internal pull u			
В	SHARE(+)	SHARE+	Active current share differential pair (see			
3	SHARE(-)	SHARE-	Full-Feature Application Notes) ⁴			
4	Vin(-)	IN RTN	Input Return			
5	Vout(-)	OUT RTN	Ouput Return			
6	SENSE(-)	-SNS	Negative remote sense ¹			
7	TRIM	TRIM	Output voltage trim ²			
8	SENSE(+)	+SNS	Positive remote sense ³			
9	Vout(+)	+VOUT	Positive output voltage			

Notes:

- 1) SENSE(-) should be connected to Vout(-) either remotely or at the converter.
- 2) Leave TRIM pin open for nominal output voltage.
- 3) SENSE(+) should be connected to Vout(+) either remotely or at the converter.
- 4) On standard product, Pin B & Pin 3 are absent

Current: 10A



®

NOTES

1) APPLIED TORQUE PER M3 OR 4-40 SCREW NOT TO EXCEED 6 in-lb (0.7 Nm)

Technical Specification

- 2) BASEPLATE FLATNESS TOLERANCE IS 0.010" (.25 mm) TIR FOR SURFACE.
- 3) PINS 1-4, 6-8 AND B ARE 0.040" (1.02 mm) DIA. WITH 0.080" (2.03 mm) DIA. STANDOFFS.
- 4) PINS 5 AND 9 ARE 0.080" (2.03 mm) DIA. WITH 0.125" (3.18 mm) DIA STANDOFFS
- 5) ALL PINS: MATERIAL: COPPER ALLOY FINISH: MATTE TIN OVER NICKEL PLATE
- 6) WEIGHT: 5.4 oz. (152 g)
- 7) ALL DIMENSIONS IN INCHES (mm) TOLERANCES: X.XX IN +/-0.02 (X.X mm +/-0.5 mm) X.XXX IN +/-0.010 (X.XX mm +/-0.25 mm)

PIN DESIGNATIONS

Pin	Name	Label	Function
1	Vin(+)	+VIN	Positive input voltage
2	ON/OFF	ON/OFF	TTL input to turn converter on and off, referenced to Vin(–), with internal pull up.
В	SHARE(+)	SHARE+	Active current share differential pair (see
3	SHARE(-)	SHARE-	Full-Feature Application Notes) ^₄
4	Vin(-)	IN RTN	Input Return
5	Vout(-)	OUT RTN	Ouput Return
6	SENSE(-)	-SNS	Negative remote sense ¹
7	TRIM	TRIM	Output voltage trim ²
8	SENSE(+)	+SNS	Positive remote sense ³
9	Vout(+)	+VOUT	Positive output voltage

Notes:

- 1) SENSE(-) should be connected to Vout(-) either remotely or at the converter.
- 2) Leave TRIM pin open for nominal output voltage.
- 3) SENSE(+) should be connected to Vout(+) either remotely or at the converter.
- 4) On standard product, Pin B & Pin 3 are absent

Support Technical Specification

MCOTS-C-28-50-HZ Output: 50V Current: 10A

Mil-COTS Qualification

Test Name	Details	# Tested (# Failed)	Consistent with MIL-STD-883F Method
Life Testing	Visual, mechanical and electrical testing before, during and after 1000 hour burn-in @ full load	15 (0)	Method 1005.8
Shock-Vibration	Visual, mechanical and electrical testing before, during and after shock and vibration tests	5 (0)	MIL-STD-202, Methods 201A & 213B
Humidity	+85 °C, 95% RH, 1000 hours, 2 minutes on / 6 hours off	8 (0)	Method 1004.7
Temperature Cycling	500 cycles of -55 °C to +100 °C (30 minute dwell at each temperature)	10 (0)	Method 1010.8, Condition A
Solderability	15 pins	15 (0)	Method 2003
DMT	-65 °C to +110 °C across full line and load specifications in 5 °C steps	7 (0)	
Altitude	70,000 feet (21 km), see Note	2 (0)	

Note: A conductive cooling design is generally needed for high altitude applications because of naturally poor convective cooling at rare atmospheres.

Mil-COTS Converter and Filter Screening

Screening		Process Description		S-Grade	M-Grade
Baseplate Operating Temperature				-55 °C to +100 °C	-55 °C to +100 °C
Storage Temperature				-65 °C to +135 °C	-65 °C to +135 °C
Pre-Cap Inspection		IPC-A-610, Class III		•	•
Temperature Cycling	MIL-STD-883	, Method 1010, Condition E	3, 10 Cycles		•
Burn-In		100 °C Baseplate		12 Hours	96 Hours
Final Electrical Test		100%		25 °C	-55 °C, +25 °C, +100 °C
Final Visual Inspection	М	IL-STD-883F, Method 2009		•	•

Mil-COTS MIL-STD-810G Qualification Testing

MIL-STD-810G Test	Method	Description		
Fungus	508.6	Table 508.6-I		
Altitude	500.5 - Proc <mark>e</mark> dure I	Storage: 70,000 ft / 2 hr duration		
Altitude	500.5 - Procedure II	Operating: 70,000 ft / 2 hr duration; Ambient Temperature		
Rapid Decompression	500.5 - Procedure III	Storage: 8,000 ft to 40,000 ft		
Acceleration	513.6 - Procedure II	Operating: 15 g		
Salt Fog	509.5	Storage		
High Temperature	501.5 - Procedure I	Storage: 135 °C / 3 hrs		
night temperature	501.5 - Procedure II	Operating: 100 °C / 3 hrs		
Low Temperature	502.5 - Procedure I	Storage: -65 °C / 4 hrs		
Low remperature	502.5 - Procedure II	Operating: -55 °C / 3 hrs		
Temperature Shock	503.5 - Procedure I - C	Storage: -65 °C to 135 °C; 12 cycles		
Rain	506.5 - Procedure I	Wind Blown Rain		
Immersion	512.5 - Procedure I	Non-Operating		
Humidity	507.5 - Procedure II	Aggravated cycle @ 95% RH (Figure 507.5-7 aggravated temp - humidity cycle, 15 cycles)		
Random Vibration	514.6 - Procedure I	10 - 2000 Hz, PSD level of 1.5 g^2 /Hz (54.6 g_{rms}), duration = 1 hr/axis		
Shock	516.6 - Procedure I	20 g peak, 11 ms, Functional Shock (Operating no load) (saw tooth)		
SHUCK	516.6 - Procedure VI	Bench Handling Shock		
Sinusoidal vibration	ation 514.6 - Category 14 Rotary wing aircraft - helicopter, 4 hrs/axis, 20 g (sine sweep from 10 - 500 Hz)			
Sand and Dust	510.5 - Procedure I	Blowing Dust		
	510.5 - Procedure II	Blowing Sand		

MCOTS-C-28-50-HZ

005-0005308 Rev. I

www.synqor.com



Ordering Information/ Part Numbering

Example MCOTS-C-28-50-HZ-N-M

Not all combinations make valid part numbers, please contact SynQor for availability. See product summary page for details.

Family	Product	Input Voltage	Output Voltage	Package	Heatsink Option	Screening Level	Options
MCOTS	C: Converter	28: 16-40 V 28E: 16-70 V 28V: 9-40 V 28VE: 9-70 V 48: 34-75 V	15: 15 V 24: 24 V 28: 28 V	HZ: Half-Brick Zeta	 N: Normal Threaded NC: Normal Threaded, with Conformal Coating F: Flanged FC: Flanged, with Conformal Coating D: Normal Non-Threaded DC: Normal Non-Threaded, with Conformal Coating 	S: S-Grade M: M-Grade	[]: Standard Feature F: Full-Feature C: High-Capacitance FC: High-Capacitance + Full-Feature

APPLICATION NOTES

A variety of application notes and technical white papers can be downloaded in pdf format from our Website.

Contact SynQor for further information and to order:

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 Swanson Road, Boxborough, MA 01719
 USA

WARRANTY

SynQor offers a two (2) year limited warranty. Complete warranty information is listed on our website or is available upon request from SynQor.

MCOTS-C-28-50-HZ

005-0005308 Rev. I

PATENTS

7,765,687

8,149,597

SynQor's patents include the following:

7,787,261

8,644,027

08/28/2024

SynQor holds numerous U.S. patents, one or more of which apply to most of its power conversion products. Any that apply to the product(s) listed in this document are identified by markings on

the product(s) or on internal components of the product(s) in accordance with U.S. patent laws.